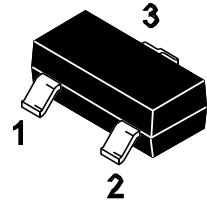


## P-Channel Enhancement Mode Power MOSFET

### Features

- Energy efficient
- Low threshold voltage
- High-speed switching
- ESD protected(HBM) up to 2KV
- Miniature surface mount package saves board space
- $V_{DS} = -50V, I_D = -0.13A$   
 $R_{DS(on)} < 8\Omega @ V_{GS} = -10V$

### SOT-23



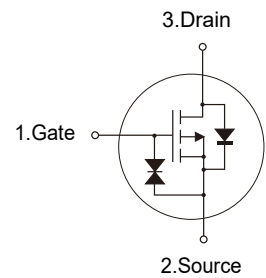
1. Gate 2. Source 3. Drain

Marking Code: P84

### Applications

- PWM applications
- Load switch
- Power management

### Schematic Diagram



### Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

| Parameter                                                | Symbol    | Value       | Unit |
|----------------------------------------------------------|-----------|-------------|------|
| Drain-Source Voltage                                     | $-V_{DS}$ | 50          | V    |
| Gate-Source Voltage                                      | $V_{GS}$  | $\pm 20$    | V    |
| Drain Current-Continuous                                 | $-I_D$    | 0.13        | A    |
| Drain Current-Pulsed <sup>Note1</sup> at $t_p < 10\mu s$ | $-I_{DM}$ | 0.52        | A    |
| Maximum Power Dissipation                                | $P_D$     | 225         | mW   |
| Junction Temperature                                     | $T_J$     | 150         | °C   |
| Storage Temperature Range                                | $T_{STG}$ | -55 to +150 | °C   |

### Thermal Characteristics

|                                                          |                 |     |      |
|----------------------------------------------------------|-----------------|-----|------|
| Thermal Resistance, Junction-to-Ambient <sup>Note2</sup> | $R_{\theta JA}$ | 556 | °C/W |
|----------------------------------------------------------|-----------------|-----|------|

## Electrical Characteristics

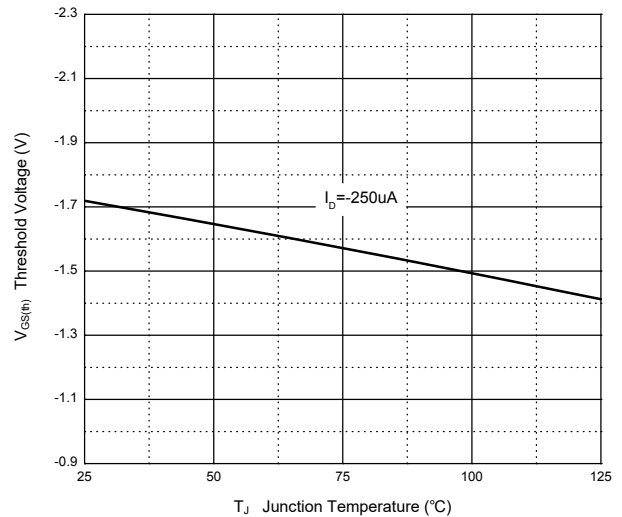
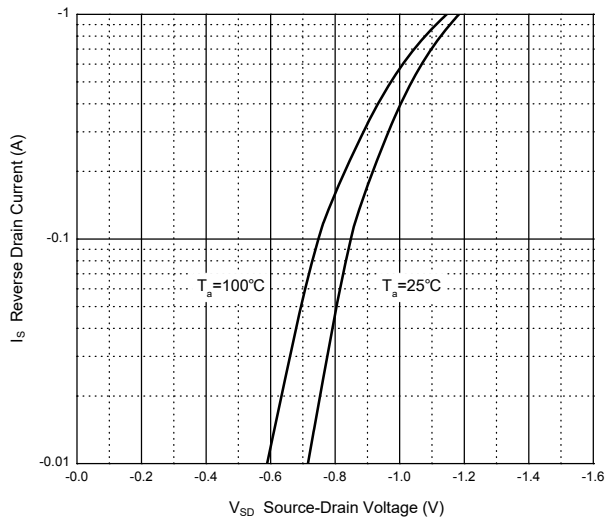
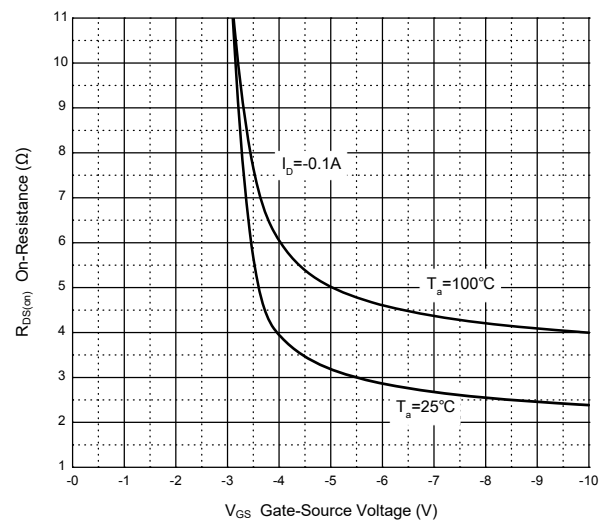
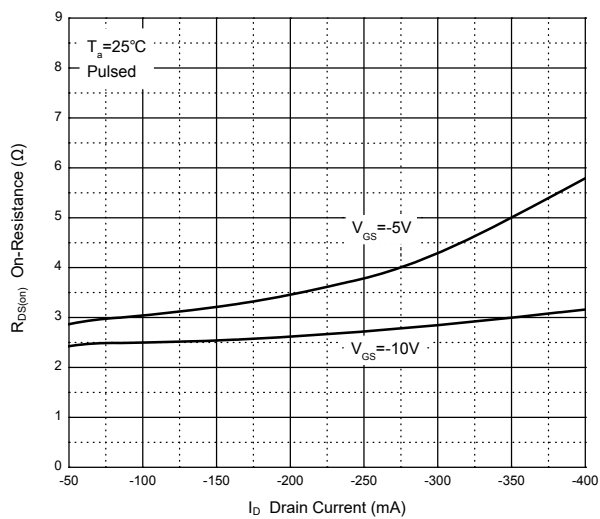
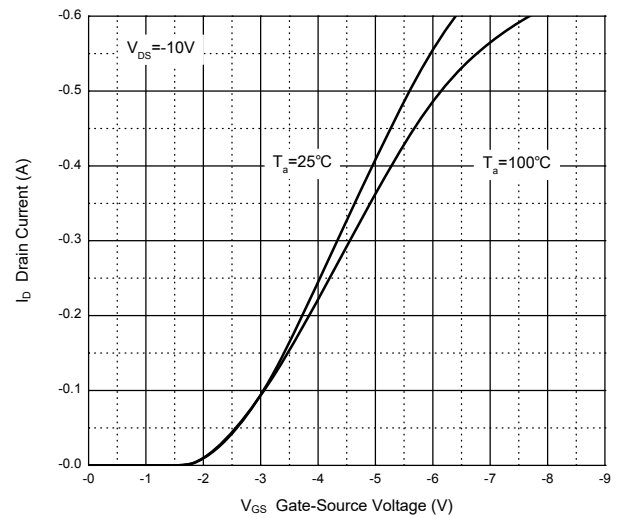
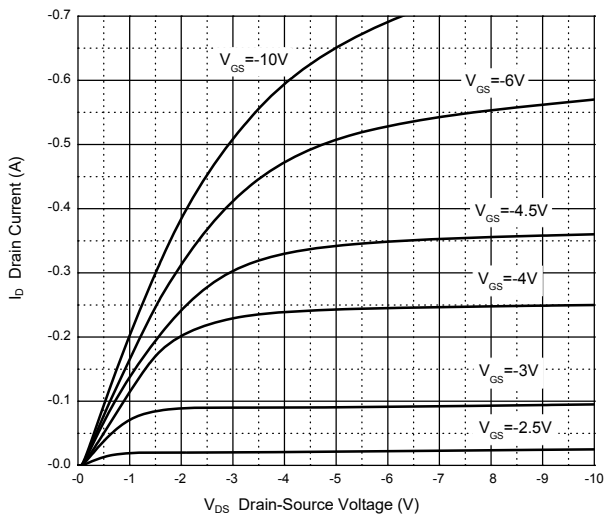
(Ta=25°C unless otherwise specified)

| Parameter                                   | Symbol         | Test Condition                                                 | Min. | Typ. | Max.     | Unit     |
|---------------------------------------------|----------------|----------------------------------------------------------------|------|------|----------|----------|
| Static Characteristics                      |                |                                                                |      |      |          |          |
| Drain-Source Breakdown Voltage              | $-V_{(BR)DSS}$ | $V_{GS}=0V, I_D=-250\mu A$                                     | 50   | --   | --       | V        |
| Zero Gate Voltage Drain Current             | $-I_{DSS}$     | $V_{DS}=-50V, V_{GS}=0V$                                       | --   | --   | 1        | $\mu A$  |
| Gate-Body Leakage Current                   | $I_{GSS}$      | $V_{GS}=\pm 20V, V_{DS}=0V$                                    | --   | --   | $\pm 10$ | $\mu A$  |
| Gate Threshold Voltage <sup>Note3</sup>     | $-V_{GS(th)}$  | $V_{DS}=V_{GS}, I_D=-250\mu A$                                 | 0.9  | 1.6  | 2        | V        |
| Drain-Source On-Resistance <sup>Note3</sup> | $R_{DS(on)}$   | $V_{GS}=-10V, I_D=-0.1A$                                       | --   | 2.5  | 8        | $\Omega$ |
|                                             |                | $V_{GS}=-5V, I_D=-0.1A$                                        | --   | 3    | 10       | $\Omega$ |
| Forward Transconductance <sup>Note3</sup>   | $g_{FS}$       | $V_{DS}=-25V, I_D=-0.1A$                                       | 0.05 | --   | --       | S        |
| Dynamic Characteristics                     |                |                                                                |      |      |          |          |
| Input Capacitance                           | $C_{iss}$      | $V_{DS}=-30V, V_{GS}=0V, f=1MHz$                               | --   | 43   | --       | pF       |
| Output Capacitance                          | $C_{oss}$      |                                                                | --   | 2.9  | --       | pF       |
| Reverse Transfer Capacitance                | $C_{rss}$      |                                                                | --   | 1.8  | --       | pF       |
| Switching Characteristics                   |                |                                                                |      |      |          |          |
| Turn-on Delay Time                          | $t_{d(on)}$    | $V_{DD}=-30V, V_{GS}=-4.5V$<br>$I_D=-0.15A, R_{GEN}=2.5\Omega$ | --   | 8.6  | --       | nS       |
| Turn-on Rise Time                           | $t_r$          |                                                                | --   | 20   | --       | nS       |
| Turn-off Delay Time                         | $t_{d(off)}$   |                                                                | --   | 15   | --       | nS       |
| Turn-off Fall Time                          | $t_f$          |                                                                | --   | 77   | --       | nS       |
| Total Gate Charge                           | $Q_g$          | $V_{DS}=-30V, I_D=0.15A$<br>$V_{GS}=-10V$                      | --   | 1.77 | --       | nC       |
| Gate-Source Charge                          | $Q_{gs}$       |                                                                | --   | 0.57 | --       | nC       |
| Gate-Drain Charge                           | $Q_{gd}$       |                                                                | --   | 0.18 | --       | nC       |
| Source-Drain Diode Characteristics          |                |                                                                |      |      |          |          |
| Diode Forward Voltage <sup>Note3</sup>      | $-V_{SD}$      | $V_{GS}=0V, I_S=-0.13A$                                        | --   | --   | 1.2      | V        |
| Diode Forward Current <sup>Note2</sup>      | $-I_S$         |                                                                | --   | --   | 0.13     | A        |

Note: 1. Repetitive rating : Pulse width limited by junction temperature.

2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.3. Pulse Test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

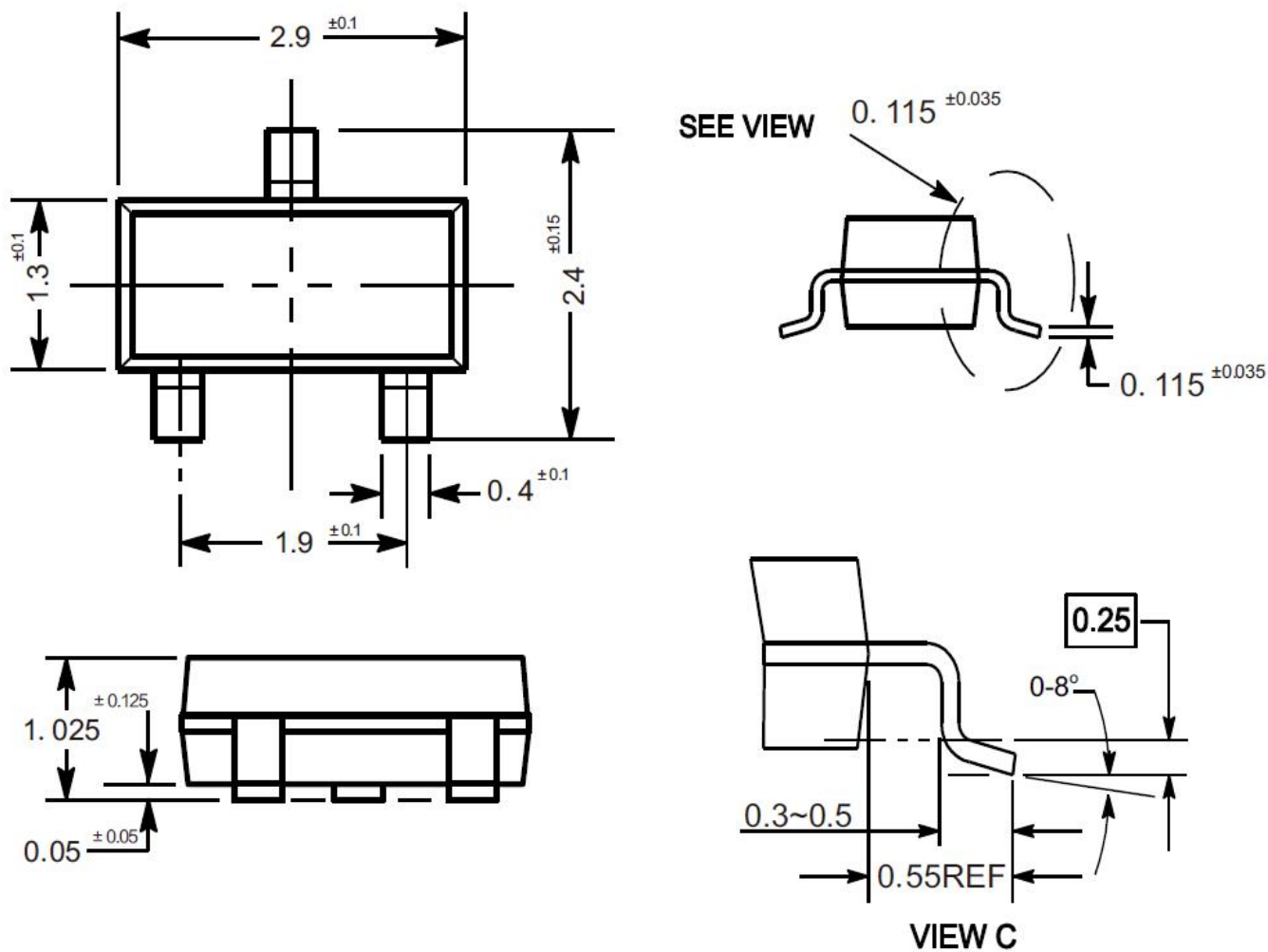
## Typical Characteristic Curves



## Package Outline

SOT-23

Dimensions in mm

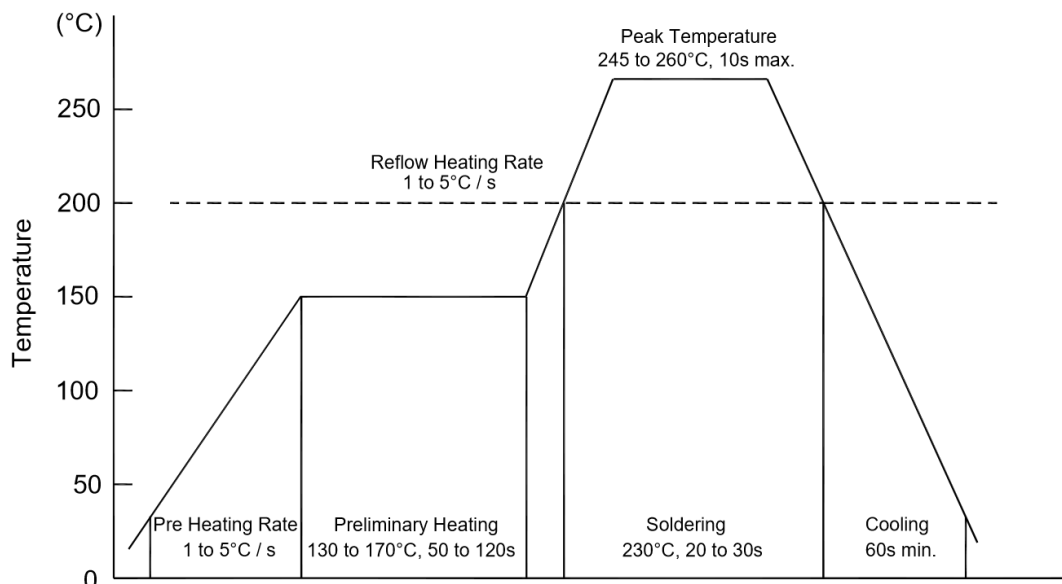


## Ordering Information

| Device  | Package | Shipping              |
|---------|---------|-----------------------|
| TN84PSA | SOT-23  | 3,000PCS/Reel&7inches |

## Conditions of Soldering and Storage

### ◆ Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

### ◆ Conditions of hand soldering

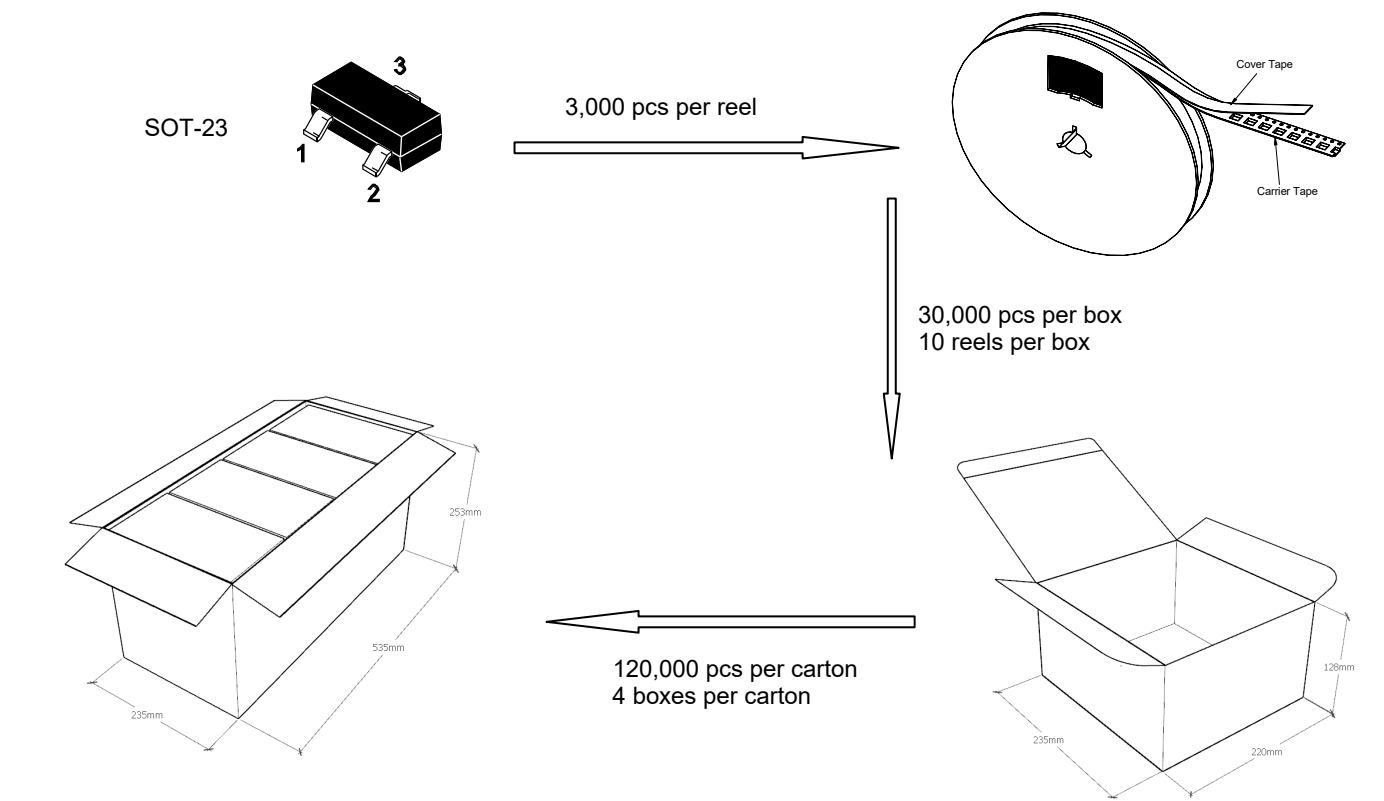
- Temperature: 370 °C
- Time: 3s max.
- Times: one time

### ◆ Storage conditions

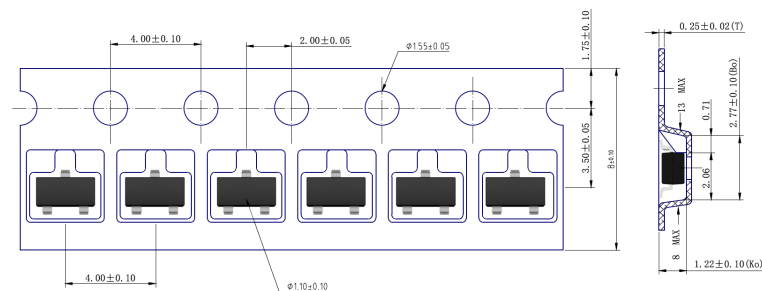
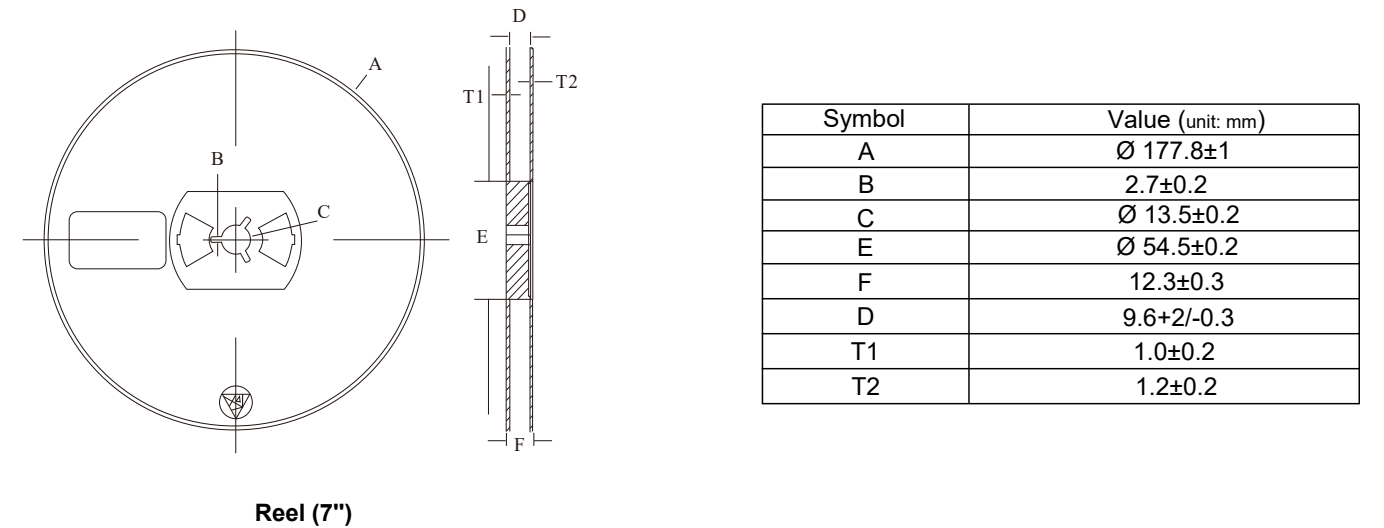
- **Temperature**  
5 to 40 °C
- **Humidity**  
30 to 80% RH
- **Recommended period**  
One year after manufacturing

Package Specifications

- The method of packaging



◆ Embossed tape and reel data



## Contact Information

TANI website: <http://www.tanisemi.com> Email: [tani@tanisemi.com](mailto:tani@tanisemi.com)

For additional information, please contact your local Sales Representative.



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### Product Specification Statement

The product specification aims to provide users with a reference regarding various product parameters, performance, and usage. It presents certain aspects of the product's performance in graphical form and is intended solely for users to select product and make product comparisons, enabling users to better understand and evaluate the characteristics and advantages of the product. It does not constitute any commitment, warranty, or guarantee.

The product parameters described in the product specification are numerical values, characteristics, and functions obtained through actual testing or theoretical calculations of the product in an independent or ideal state. Due to the complexity of product applications and variations in test conditions and equipment, there may be slight fluctuations in parameter test values. TANI shall not guarantee that the actual performance of the product when installed in the customer's system or equipment will be entirely consistent with the product specification, especially concerning dynamic parameters. It is recommended that users consult with professionals for product selection and system design. Users should also thoroughly validate and assess whether the actual parameters and performance when installed in their respective systems or equipment meet their requirements or expectations. Additionally, users should exercise caution in verifying product compatibility issues, and TANI assumes no responsibility for the application of the product. TANI strives to provide accurate and up-to-date information to the best of our ability. However, due to technical, human, or other reasons, TANI cannot guarantee that the information provided in the product specification is entirely accurate and error-free. TANI shall not be held responsible for any losses or damages resulting from the use or reliance on any information in these product specifications.

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